

Title (en)  
SUBSTRATE FOR MOUNTING LED

Title (de)  
TRÄGERSUBSTRAT FÜR LED

Title (fr)  
SUBSTRAT DE MONTAGE DE DEL

Publication  
**EP 2985794 A4 20170308 (EN)**

Application  
**EP 14782793 A 20140203**

Priority  
• JP 2013080476 A 20130408  
• JP 2014052405 W 20140203

Abstract (en)  
[origin: EP2985794A1] Provided is a low-cost LED mounting substrate capable of allowing an emission color of an LED to be clearly output, without being additionally subjected to coating. The LED mounting substrate comprises a flexible insulating substrate (1) made of a paper material, and a circuit pattern (2) composed mainly of solder and coveringly attached onto the insulating substrate (1) in such a manner as to include an LED mounting land.

IPC 8 full level  
**H01L 33/62** (2010.01); **H01L 33/48** (2010.01); **H05K 1/03** (2006.01); **H05K 1/02** (2006.01)

CPC (source: EP)  
**H05K 1/0386** (2013.01); **H01L 33/486** (2013.01); **H05K 1/0209** (2013.01); **H05K 2201/10106** (2013.01)

Citation (search report)  
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Designated contracting state (EPC)  
AL AT BE BG CH CY CZ DE DK EE ES FI FR GB GR HR HU IE IS IT LI LT LU LV MC MK MT NL NO PL PT RO RS SE SI SK SM TR

DOCDB simple family (publication)  
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DOCDB simple family (application)  
**EP 14782793 A 20140203**; HK 16108514 A 20160719; JP 2013080476 A 20130408; JP 2014052405 W 20140203